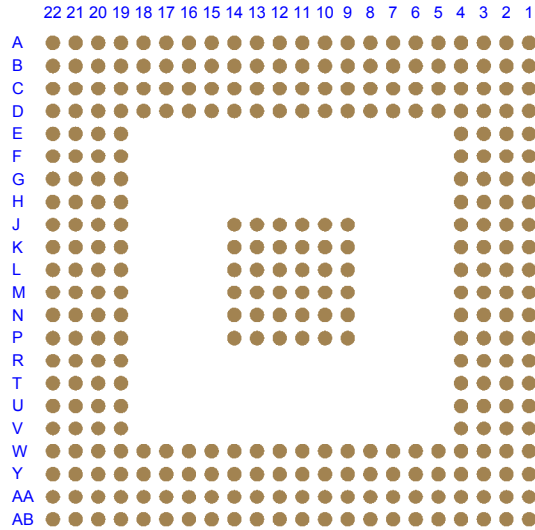


- Notes: (Unless Otherwise Specified).
- 1) ALL DIMENSIONS ARE IN MM.
 - 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
 - 3) BALL DIAMETER (BEFORE REFLOW): 0.635 (25 MIL).
 - 4) SOLDER MASK DEFINED PAD OPENING: 0.508mm (20 MIL).
 - 5) PAD Cu DIAMETER: 0.635mm (25 MIL).
 - 6) SUBSTRATE MATERIAL: BT (ALTERNATE FR4).
 - 7) DUMMY DIE IS OPTIONAL.
 - 8) DAISY CHAIN PATTERN (SEE PAGE 2).
 - 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR SOLDERING TO PC BOARD.

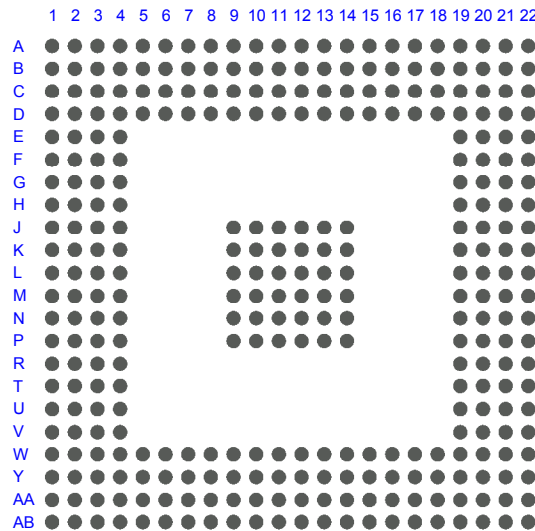
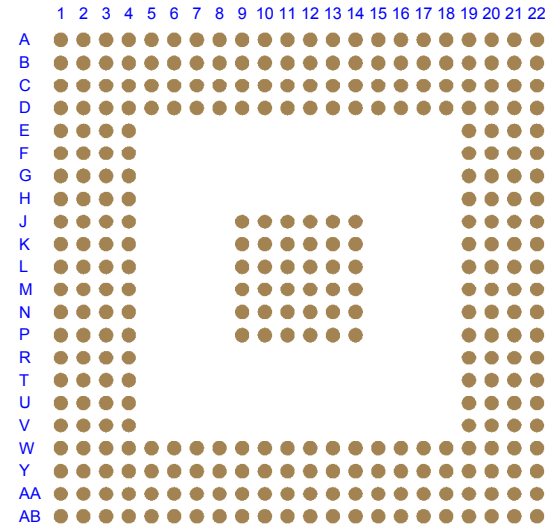
PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-Free	RoHS	Si DIE
LBGA324T1.0-C-ISO-D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
LBGA324T1.0-C-ISO	Sn96.5/Ag3.0/Cu0.5	YES	YES	NO
LBGA324T1.0-ISO-D	Sn63/Pb37	NO	NO	YES
LBGA324T1.0-ISO	Sn63/Pb37	NO	NO	NO

APPROVALS	DATE				
DRAWN T.Au	1/14/14				
ENG M. Hart	1/14/14	TITLE		LBGA324T1.0C-ISO ISOLATED DUMMY	
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		3.7:1	A	512201	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 2
REVISED					

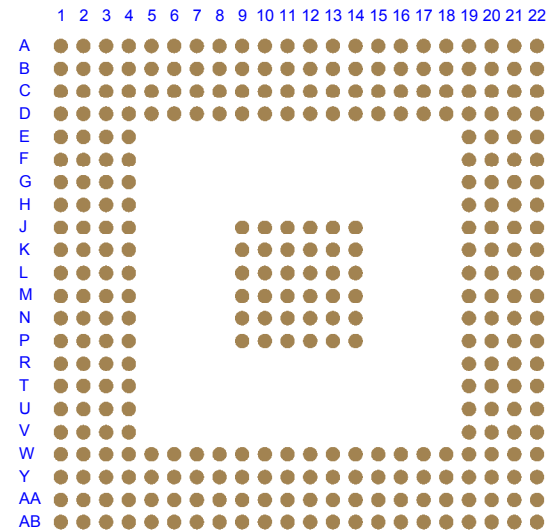
BALL VIEW



BOTTOM SIDE (TOP X-RAY VIEW)



TEST VEHICLE BOARD



AFTER MOUNTING

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.635mm (25 MIL).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.152mm (6 MIL).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING: 0.508mm (20 MIL).

TopLine[®]			
TITLE		LBGA324T1.0C-ISO ISOLATED DUMMY	
SCALE	SIZE	DRAWING NO.	REV
3:1	A	512201	A
DO NOT SCALE DRAWING			SHEET 2 OF 2